

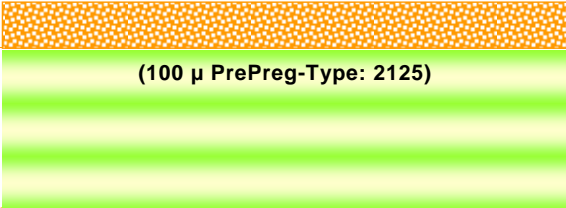
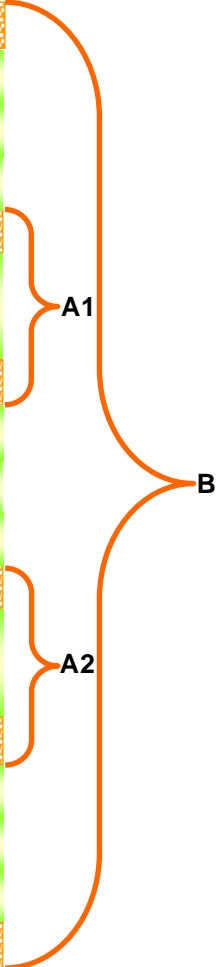
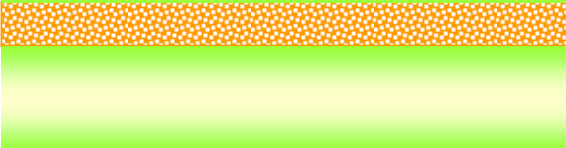
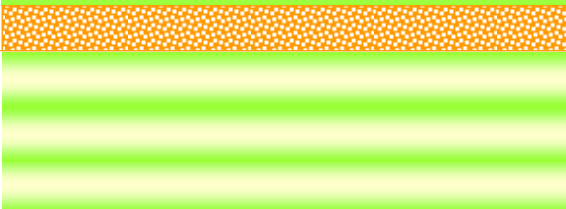

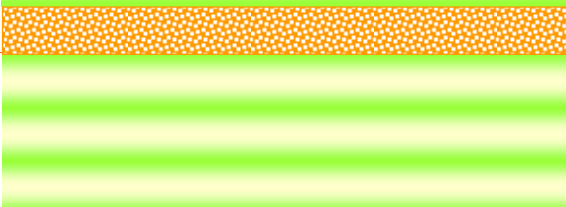

Schematic Key for Multilayer and HDI-Technology Build-Ups

a	b	c	d	e	f	g + h + i
---	---	---	---	---	---	-----------

06 193 FR4 35 L41.35 P10

columns and equal kind of positions are separated by "_". Equal prefixes in one column are reduced to one.

06_193_FR4_35_L41.35_p10

Layers	in μ	Material	Build-Up	Assembly	
Layer-1	35 μ	Copper			
	100 μ	Prepreg			
	100 μ	Prepreg			
	100 μ	Prepreg			
Layer-2	35 μ	Copper			A1
	410 μ	L-FR4			
Layer-3	35 μ	Copper			B
	100 μ	Prepreg			
	100 μ	Prepreg			
	100 μ	Prepreg			
Layer-4	35 μ	Copper		A2	
	410 μ	L-FR4			
Layer-5	35 μ	Copper			
	100 μ	Prepreg			
	100 μ	Prepreg			
	100 μ	Prepreg			
Layer-99	35 μ	Copper			

© Copyright by Printed Circuit Boards GmbH